

FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
MICRON.110AAPPLICATION NO.
09/471,071INFORMATION DISCLOSURE STATEMENT
BY APPLICANT

(USE SEVERAL SHEETS IF NECESSARY)

APPLICANT
Tongbi JiangFILING DATE
December 21, 1999GROUP
2835

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
JHA	5,045,921	09/03/91	Lin et al.			
JHA	5,216,278	06/01/93	Lin et al.			
JHA	5,659,952	08/26/97	Kovac et al.			
JHA	5,821,609	10/13/98	DiStefano et al.			
JHA	5,879,965	03/09/99	Jiang et al.			

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

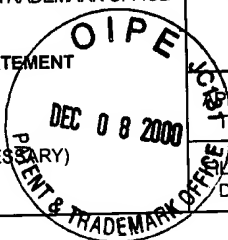
OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

EXAMINER INITIAL	
JHA	

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EXAMINER	<i>Joseph H. Alchier</i>	DATE CONSIDERED	<i>11/28/01</i>
*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.			

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U.S. PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)	
JHA	5,148,266	09/15/92	Khandros et al.				
JHA	6,012,224	01/11/00	DiStefano et al.				

FOREIGN PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)
JHA	"Area Tape Automated Bonding Ball Grid Array Technology" by Chin-Ching Huang and Ahmad Hamzehdoost, Ball Grid Array Technology, Chapter 14, pgs. 443-464 (1995)
JHA	"Face-down BGA shrinks memory products by 75%", by Spencer Chin, Outlook
JHA	"Tessera's Micro-Ball Grid Array (μ BGA)", Chapter 16, pgs. 259-282
JHA	"Advanced Encapsulant Systems for Flip-Chip-on-Board Assemblies: Underfills with Improved manufacturing Properties" by Daniel R. Gamota and Cindy M. Melton, IEEE Transactions on Components, Packaging, and Manufacturing Technology - Part C, Vol. 21, No. 3, July 1998

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EXAMINER <i>Joseph A. Alcorn</i>	DATE CONSIDERED 11/28/01
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